

[Document Type] ABSTRACT

[Abstract]

[Object]

To provide a treatment apparatus capable of instantly starting a cooling treatment of a heat-treated substrate so as to improve a yield rate.

[Means for Solving the Problems]

A treatment apparatus according to the present invention comprises a casing 26 provided therein with a heating and mounting table 27 for performing heat treatment of a wafer W mounted thereon and a cooling and mounting table 28 for performing cooling treatment of the wafer W mounted thereon. In order to intercept heat generated in the heating and mounting table 27, a cover 45 for covering the heating and mounting table 27 is provided and a circulation passage 52, in which constant-temperature water flows from a constant-temperature water supply source 53, is formed in the cooling and mounting table 28. The cooling and mounting table 28 can move by a moving means 55 in the casing 26 to receive the wafer W immediately after completing heat treatment.

[Selected Drawing]

Fig. 3